ASSOCIATION	© Copyright 2005. Il CS INDUSTRIES® international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa					ation				
Supplie	r Information														
Company name* Company unique ID					τ	Unique ID Authority					Response Date*				
nsemi											2023-06-08				
Contact N	lame		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards	Product Envi	ro Compliance	NA Product-Env-Stewards@onsemi.com					0 m						
	Requester Item Number Mfr Item		Number	Mfr Item Name	Name Effective Date Version Manufac		Manufact	uring Site	ng Site Weight		UOM	Unit Type			
		AR1820I A0-DR	HSSC00SHE	18 MP 1/2.3 CIS			2023-06-08		,	TA1		2	55.05	mg	Each
Ianufa	cturing Proccess Informa	tion													
	Terminal Plating / Grid Array Material Ter		erminal Base A	ninal Base Alloy J-STD-020 MSL		Rating	Peak Process Body Temperatur		re Max Time at Peak Tempera		Temperatu	ire Nun	nber of Reflow Cy	cles	
	SnAgCu	C	CU Alloy	4	ļ		260		С	30		second	ls 3		
omments	3														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	ective 2011/65/EU (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).												
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of								
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all								
Exemption List Version	EL-2011/534/EU												
Declaration Signature													
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the								
Supplier Digital Signature Ra	stislav Drska	Le											

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	42.75	mg		Misc.	proprietary data		0.1625	mg
			Supplier	Silicon (Si)	7440-21-3		42.1643	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4232	mg
Die Attach	1.88	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.705	mg
			Supplier	Ethylene Glycol	107-21-1		0.0188	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0564	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.3948	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.705	mg
maging Lens	45.38	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.269	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.269	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.269	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.269	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2269	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.269	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.269	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		31.5391	mg
Lid Attach	1.95	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.6162	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1014	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.6162	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.6162	mg
Mold Compound-Black	40.5	mg		Phenolic Resin	proprietary data		6.075	mg
			Supplier	Oxirane	39817-09-9		6.075	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.215	mg
			Supplier	Carbon Black (C)	1333-86-4		0.405	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.92	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.81	mg
older Ball	35.02	mg	Supplier	Silver (Ag)	7440-22-4		1.0506	mg
			Supplier	Tin (Sn)	7440-31-5		33.7943	mg
			Supplier	Copper (Cu)	7440-50-8		0.1751	mg
Substrate and Solder Mask	87.4	mg	Supplier	Acetophenone	98-86-2		1.713	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		19.3941	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.1449	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	1.1537	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2884	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2884	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4261	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.74	mg
			Supplier	Copper (Cu)	7440-50-8	42.389	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.8624	mg
Wire Bond - Au	0.17	mg	Supplier	Gold (Au)	7440-57-5	0.17	mg